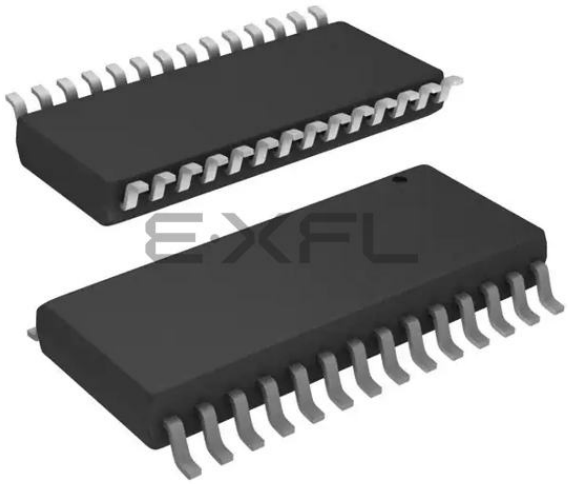

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2610-i-so

TABLE 2-1: PIN DESCRIPTIONS (DURING PROGRAMMING): PIC18F2XXX/4XXX FAMILY

Pin Name	During Programming		
	Pin Name	Pin Type	Pin Description
$\overline{MCLR}$/VPP/RE3	VPP	P	Programming Enable
VDD(2)	VDD	P	Power Supply
VSS(2)	VSS	P	Ground
RB5	PGM	I	Low-Voltage ICSP™ Input when LVP Configuration bit equals '1'(1)
RB6	PGC	I	Serial Clock
RB7	PGD	I/O	Serial Data

Legend: I = Input, O = Output, P = Power
Note 1: See Figure 5-1 for more information.
2: All power supply (VDD) and ground (VSS) pins must be connected.

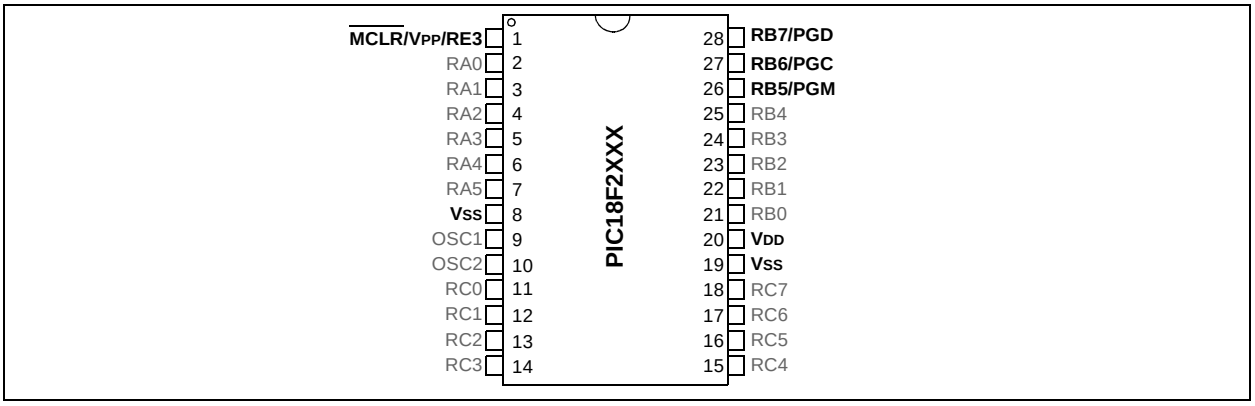
The following devices are included in 28-pin SPDIP, PDIP and SOIC parts:

- PIC18F2221
- PIC18F2321
- PIC18F2410
- PIC18F2420
- PIC18F2423
- PIC18F2450
- PIC18F2455
- PIC18F2458
- PIC18F2480
- PIC18F2510
- PIC18F2515
- PIC18F2520
- PIC18F2523
- PIC18F2525
- PIC18F2550
- PIC18F2553
- PIC18F2580
- PIC18F2585
- PIC18F2610
- PIC18F2620
- PIC18F2680
- PIC18F2682
- PIC18F2685

The following devices are included in 28-pin SSOP parts:

- PIC18F2221
- PIC18F2321

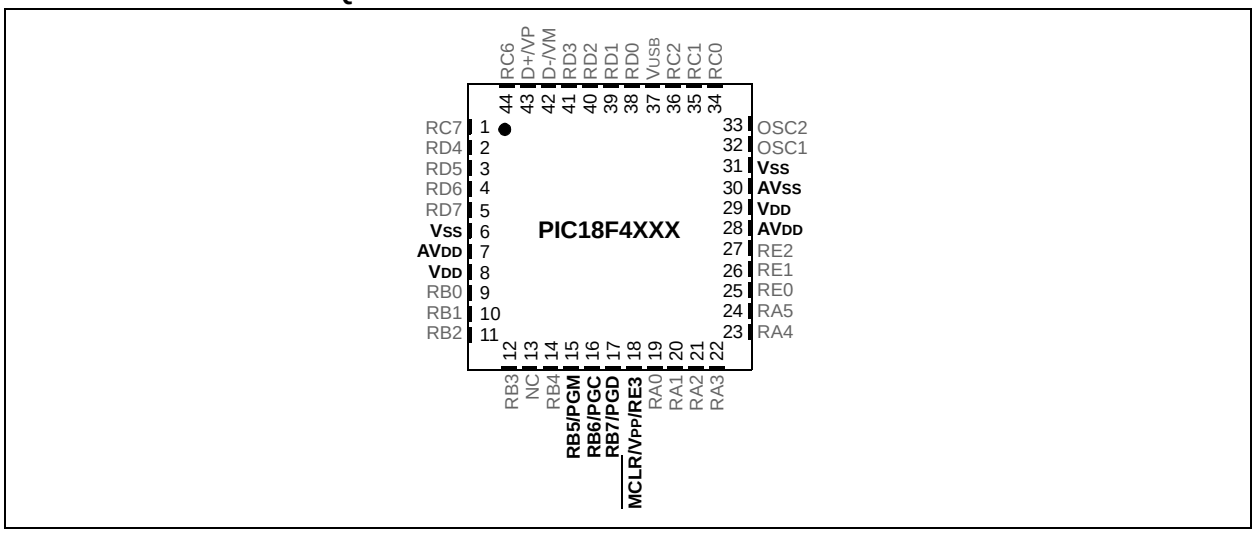
FIGURE 2-1: 28-Pin SPDIP, PDIP, SOIC,SSOP



The following devices are included in 44-pin QFN parts:

- PIC18F4221
- PIC18F4321
- PIC18F4410
- PIC18F4420
- PIC18F4423
- PIC18F4450
- PIC18F4455
- PIC18F4458
- PIC18F4480
- PIC18F4510
- PIC18F4520
- PIC18F4515
- PIC18F4523
- PIC18F4525
- PIC18F4550
- PIC18F4553
- PIC18F4580
- PIC18F4585
- PIC18F4610
- PIC18F4620
- PIC18F4680
- PIC18F4682
- PIC18F4685

FIGURE 2-5: 44-PIN QFN



2.3 Memory Maps

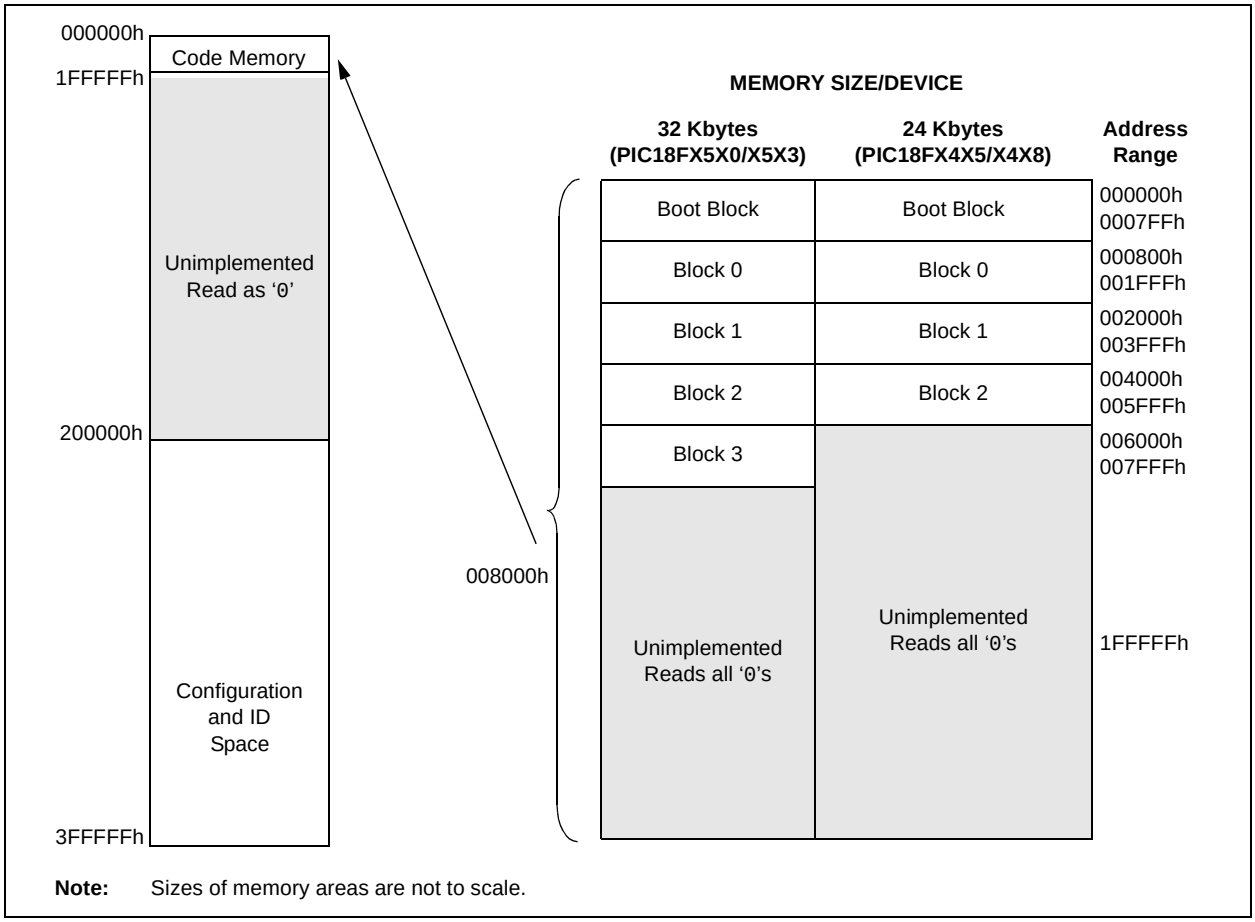
For PIC18FX6X0 devices, the code memory space extends from 0000h to 0FFFFh (64 Kbytes) in four 16-Kbyte blocks. For PIC18FX5X5 devices, the code memory space extends from 0000h to 0BFFFFh (48 Kbytes) in three 16-Kbyte blocks. Addresses, 0000h through 07FFh, however, define a “Boot Block” region that is treated separately from Block 0. All of these blocks define code protection boundaries within the code memory space.

The size of the Boot Block in PIC18F2585/2680/4585/4680 devices can be configured as 1, 2 or 4K words (see Figure 2-6). This is done through the BBSIZ<1:0> bits in the Configuration register, CONFIG4L. It is important to note that increasing the size of the Boot Block decreases the size of Block 0.

TABLE 2-4: IMPLEMENTATION OF CODE MEMORY

Device	Code Memory Size (Bytes)
PIC18F2455	000000h-005FFFh (24K)
PIC18F2458	
PIC18F4455	
PIC18F4458	
PIC18F2510	000000h-007FFFh (32K)
PIC18F2520	
PIC18F2523	
PIC18F2550	
PIC18F2553	
PIC18F4510	
PIC18F4520	
PIC18F4523	
PIC18F4550	
PIC18F4553	

FIGURE 2-8: MEMORY MAP AND THE CODE MEMORY SPACE FOR PIC18FX4X5/X4X8/X5X0/X5X3 DEVICES



Note: Sizes of memory areas are not to scale.

For PIC18FX4X0/X4X3 devices, the code memory space extends from 000000h to 003FFFh (16 Kbytes) in two 8-Kbyte blocks. Addresses, 000000h through 0003FFh, however, define a “Boot Block” region that is treated separately from Block 0. All of these blocks define code protection boundaries within the code memory space.

In addition to the code memory space, there are three blocks that are accessible to the user through Table Reads and Table Writes. Their locations in the memory map are shown in Figure 2-12.

Users may store identification information (ID) in eight ID registers. These ID registers are mapped in addresses, 200000h through 200007h. The ID locations read out normally, even after code protection is applied.

Locations, 300000h through 30000Dh, are reserved for the Configuration bits. These bits select various device options and are described in **Section 5.0 "Configuration Word"**. These Configuration bits read out normally, even after code protection.

Locations, 3FFFFEh and 3FFFFFh, are reserved for the Device ID bits. These bits may be used by the programmer to identify what device type is being programmed and are described in **Section 5.0 "Configuration Word"**. These Device ID bits read out normally, even after code protection.

2.3.1 MEMORY ADDRESS POINTER

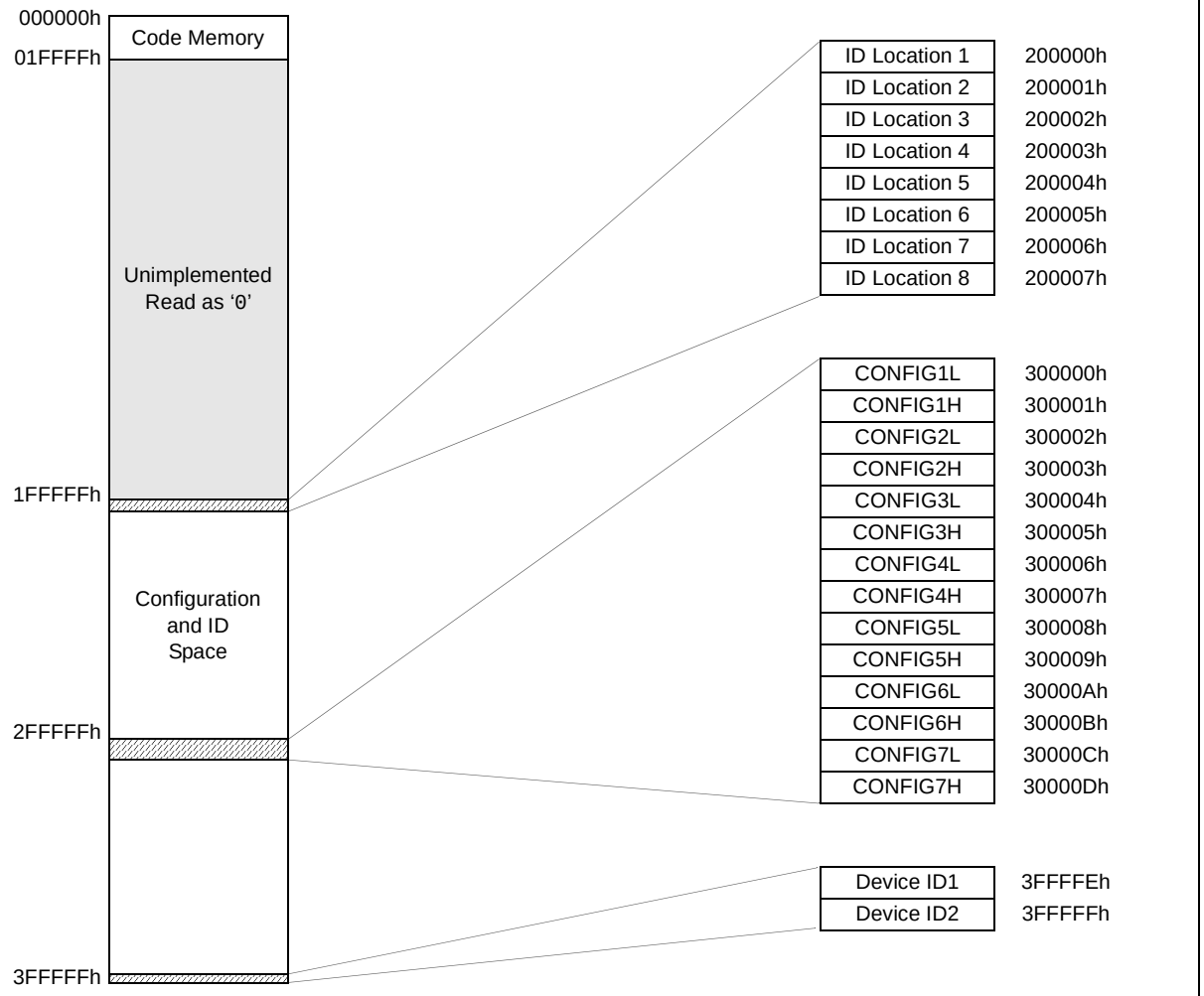
Memory in the address space, 0000000h to 3FFFFFh, is addressed via the Table Pointer register, which is comprised of three pointer registers:

- TBLPTRU at RAM address 0FF8h
- TBLPTRH at RAM address 0FF7h
- TBLPTRL at RAM address 0FF6h

TBLPTRU	TBLPTRH	TBLPTRL
Addr[21:16]	Addr[15:8]	Addr[7:0]

The 4-bit command, '0000' (core instruction), is used to load the Table Pointer prior to using many read or write operations.

FIGURE 2-12: CONFIGURATION AND ID LOCATIONS FOR PIC18F2XXX/4XXX FAMILY DEVICES



Note: Sizes of memory areas are not to scale.

2.5 Entering and Exiting High-Voltage ICSP Program/Verify Mode

As shown in Figure 2-14, the High-Voltage ICSP Program/Verify mode is entered by holding PGC and PGD low and then raising $\overline{MCLR}$/VPP/RE3 to VIHH (high voltage). Once in this mode, the code memory, data EEPROM (selected devices only, see **Section 3.3 "Data EEPROM Programming"**), ID locations and Configuration bits can be accessed and programmed in serial fashion. Figure 2-15 shows the exit sequence.

The sequence that enters the device into the Program/Verify mode places all unused I/Os in the high-impedance state.

FIGURE 2-14: ENTERING HIGH-VOLTAGE PROGRAM/VERIFY MODE

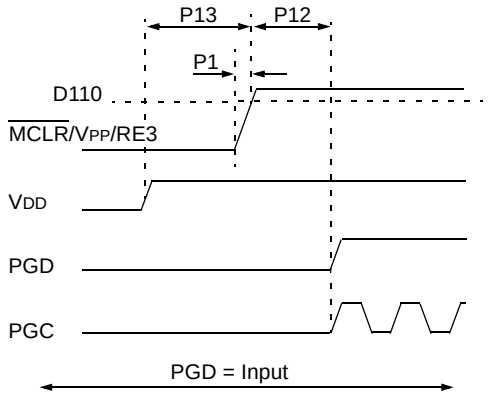
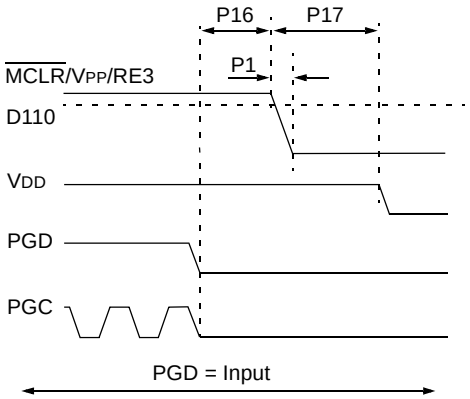


FIGURE 2-15: EXITING HIGH-VOLTAGE PROGRAM/VERIFY MODE



2.7 Serial Program/Verify Operation

The PGC pin is used as a clock input pin and the PGD pin is used for entering command bits and data input/output during serial operation. Commands and data are transmitted on the rising edge of PGC, latched on the falling edge of PGC and are Least Significant bit (LSb) first.

2.7.1 4-BIT COMMANDS

All instructions are 20 bits, consisting of a leading 4-bit command followed by a 16-bit operand, which depends on the type of command being executed. To input a command, PGC is cycled four times. The commands needed for programming and verification are shown in Table 2-8.

Depending on the 4-bit command, the 16-bit operand represents 16 bits of input data or 8 bits of input data and 8 bits of output data.

Throughout this specification, commands and data are presented as illustrated in Table 2-9. The 4-bit command is shown Most Significant bit (MSb) first. The command operand, or “Data Payload”, is shown as <MSB><LSB>. Figure 2-18 demonstrates how to serially present a 20-bit command/operand to the device.

2.7.2 CORE INSTRUCTION

The core instruction passes a 16-bit instruction to the CPU core for execution. This is needed to set up registers as appropriate for use with other commands.

TABLE 2-8: COMMANDS FOR PROGRAMMING

Description	4-Bit Command
Core Instruction (Shift in16-bit instruction)	0000
Shift Out TABLAT Register	0010
Table Read	1000
Table Read, Post-Increment	1001
Table Read, Post-Decrement	1010
Table Read, Pre-Increment	1011
Table Write	1100
Table Write, Post-Increment by 2	1101
Table Write, Start Programming, Post-Increment by 2	1110
Table Write, Start Programming	1111

TABLE 2-9: SAMPLE COMMAND SEQUENCE

4-Bit Command	Data Payload	Core Instruction
1101	3C 40	Table Write, post-increment by 2

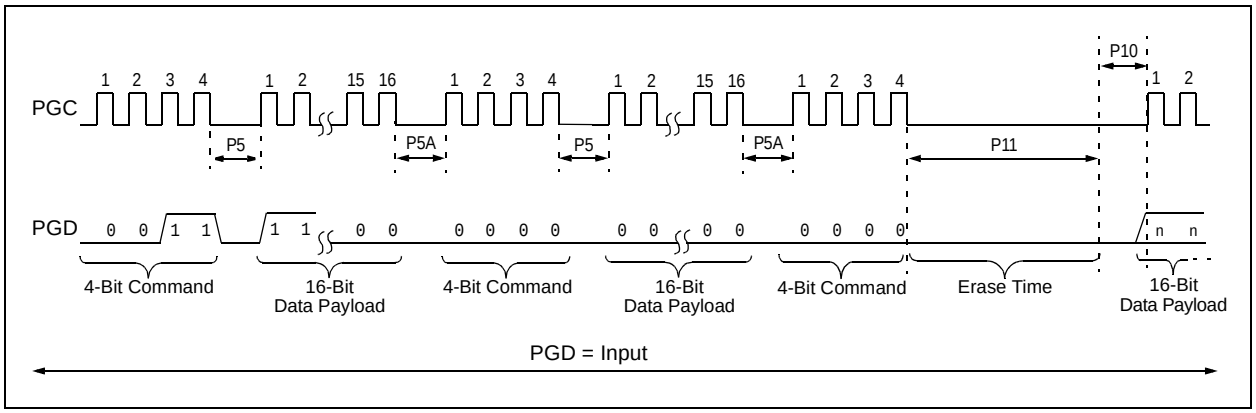
3.1.2 LOW-VOLTAGE ICSP BULK ERASE

When using low-voltage ICSP, the part must be supplied by the voltage specified in Parameter D111 if a Bulk Erase is to be executed. All other Bulk Erase details, as described above, apply.

If it is determined that a program memory erase must be performed at a supply voltage below the Bulk Erase limit, refer to the erase methodology described in **Section 3.1.3 "ICSP Row Erase"** and **Section 3.2.1 "Modifying Code Memory"**.

If it is determined that a data EEPROM erase (selected devices only, see **Section 3.3 "Data EEPROM Programming"**) must be performed at a supply voltage below the Bulk Erase limit, follow the methodology described in **Section 3.3 "Data EEPROM Programming"** and write '1's to the array.

FIGURE 3-2: BULK ERASE TIMING



3.1.3 ICSP ROW ERASE

Regardless of whether high or low-voltage ICSP is used, it is possible to erase one row (64 bytes of data), provided the block is not code or write-protected. Rows are located at static boundaries, beginning at program memory address, 000000h, extending to the internal program memory limit (see **Section 2.3 "Memory Maps"**).

The Row Erase duration is externally timed and is controlled by PGC. After the WR bit in EECON1 is set, a NOP is issued, where the 4th PGC is held high for the duration of the programming time, P9.

After PGC is brought low, the programming sequence is terminated. PGC must be held low for the time specified by Parameter P10 to allow high-voltage discharge of the memory array.

The code sequence to Row Erase a PIC18F2XXX/4XXX Family device is shown in Table 3-3. The flowchart, shown in Figure 3-3, depicts the logic necessary to completely erase a PIC18F2XXX/4XXX Family device. The timing diagram that details the Start Programming command and Parameters P9 and P10 is shown in Figure 3-5.

Note:	The TBLPTR register can point to any byte within the row intended for erase.

3.3 Data EEPROM Programming

Note: Data EEPROM programming is **not** available on the following devices:	
PIC18F2410	PIC18F4410
PIC18F2450	PIC18F4450
PIC18F2510	PIC18F4510
PIC18F2515	PIC18F4515
PIC18F2610	PIC18F4610

Data EEPROM is accessed one byte at a time via an Address Pointer (register pair: EEADRH:EEADR) and a data latch (EEDATA). Data EEPROM is written by loading EEADRH:EEADR with the desired memory location, EEDATA, with the data to be written and initiating a memory write by appropriately configuring the EECON1 register. A byte write automatically erases the location and writes the new data (erase-before-write).

When using the EECON1 register to perform a data EEPROM write, both the EEPGD and CFGS bits must be cleared (EECON1<7:6> = 00). The WREN bit must be set (EECON1<2> = 1) to enable writes of any sort and this must be done prior to initiating a write sequence. The write sequence is initiated by setting the WR bit (EECON1<1> = 1).

The write begins on the falling edge of the 4th PGC after the WR bit is set. It ends when the WR bit is cleared by hardware.

After the programming sequence terminates, PGC must still be held low for the time specified by Parameter P10 to allow high-voltage discharge of the memory array.

FIGURE 3-6: PROGRAM DATA FLOW

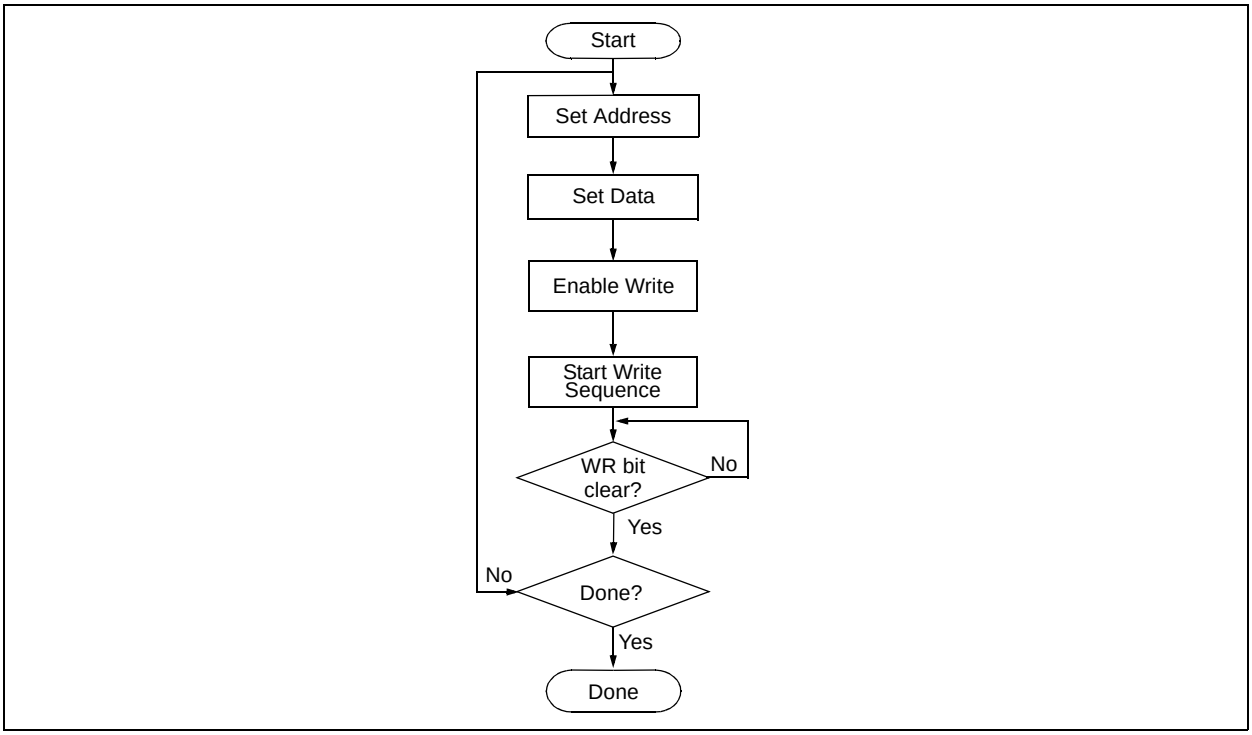
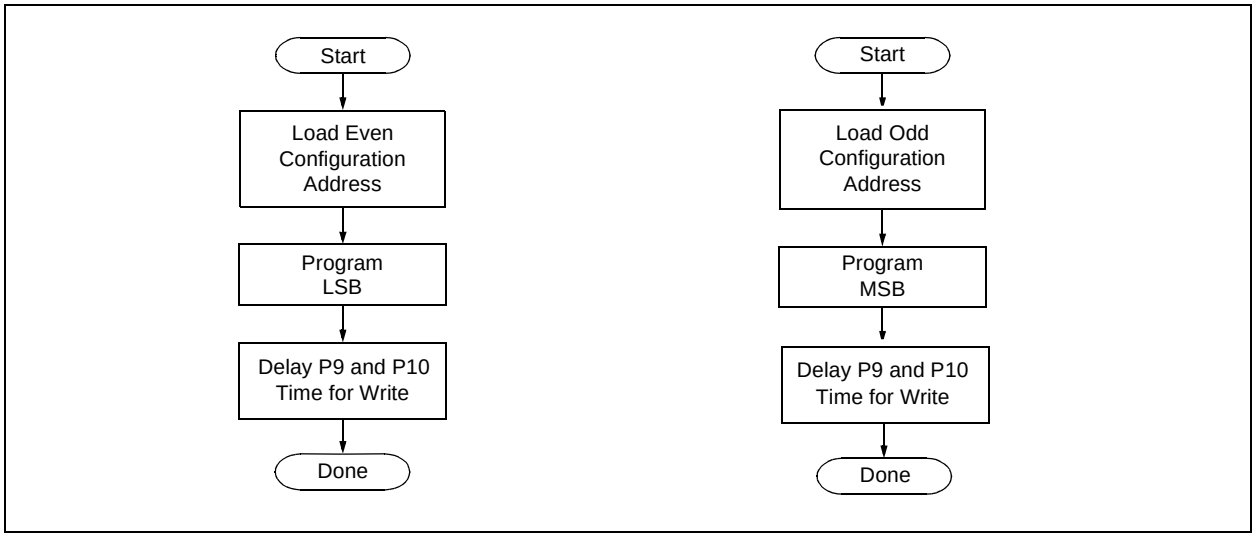


TABLE 3-9: SET ADDRESS POINTER TO CONFIGURATION LOCATION

4-Bit Command	Data Payload	Core Instruction
Step 1: Enable writes and direct access to configuration memory.		
0000	8E A6	BSF EECON1, EEPGD
0000	8C A6	BSF EECON1, CFGS
Step 2: Set Table Pointer for configuration byte to be written. Write even/odd addresses.(1)		
0000	0E 30	MOVLW 30h
0000	6E F8	MOVWF TBLPTRU
0000	0E 00	MOVLW 00h
0000	6E F7	MOVWF TBLPRTH
0000	0E 00	MOVLW 00h
0000	6E F6	MOVWF TBLPTRL
1111	<MSB ignored><LSB>	Load 2 bytes and start programming.
0000	00 00	NOP - hold PGC high for time P9 and low for time P10.
0000	0E 01	MOVLW 01h
0000	6E F6	MOVWF TBLPTRL
1111	<MSB><LSB ignored>	Load 2 bytes and start programming.
0000	00 00	NOP - hold PGC high for time P9 and low for time P10.

Note 1: Enabling the write protection of Configuration bits (WRTC = 0 in CONFIG6H) will prevent further writing of the Configuration bits. Always write all the Configuration bits before enabling the write protection for Configuration bits.

FIGURE 3-8: CONFIGURATION PROGRAMMING FLOW

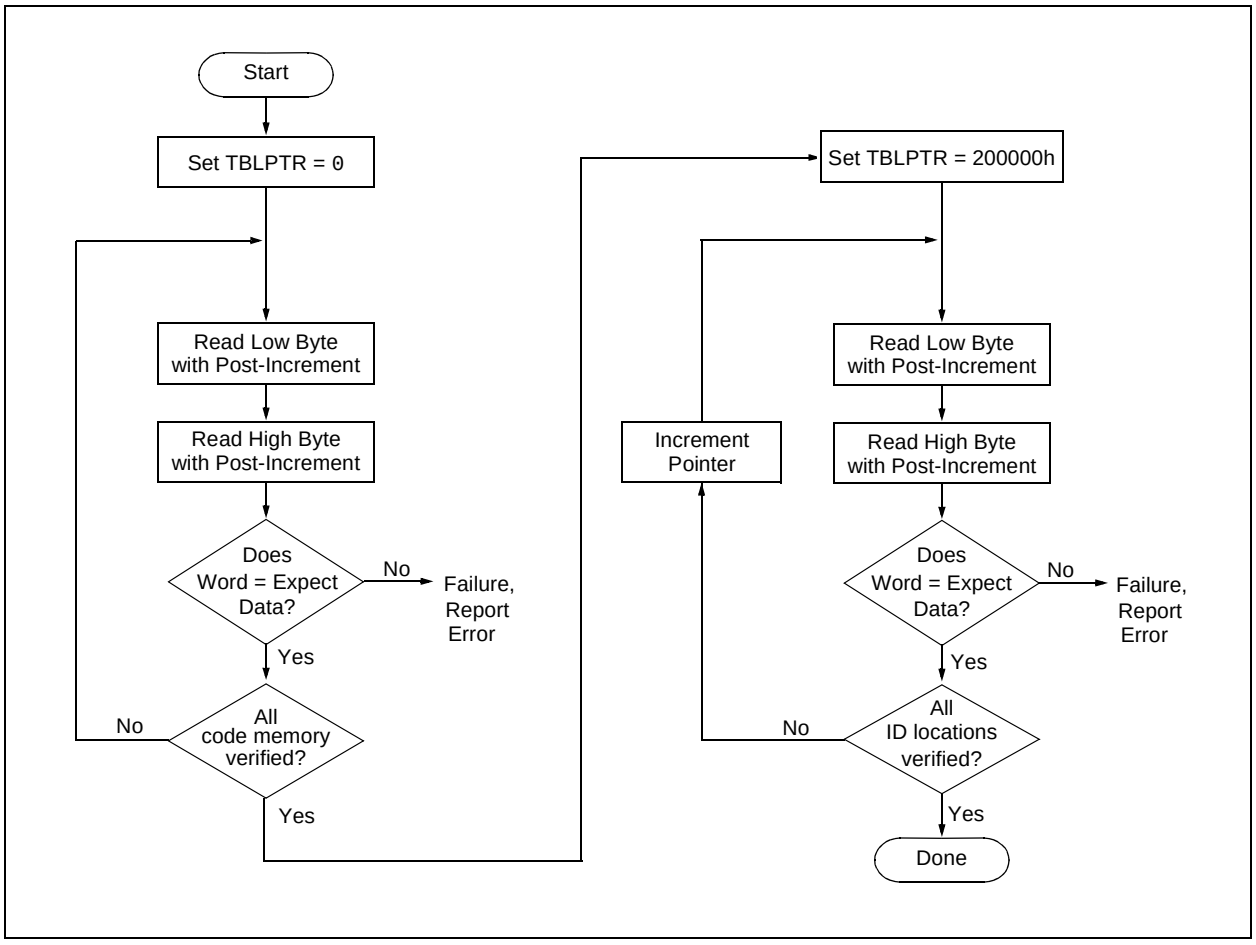


4.2 Verify Code Memory and ID Locations

The verify step involves reading back the code memory space and comparing it against the copy held in the programmer's buffer. Memory reads occur a single byte at a time, so two bytes must be read to compare against the word in the programmer's buffer. Refer to **Section 4.1 "Read Code Memory, ID Locations and Configuration Bits"** for implementation details of reading code memory.

The Table Pointer must be manually set to 200000h (base address of the ID locations) once the code memory has been verified. The post-increment feature of the Table Read 4-bit command may not be used to increment the Table Pointer beyond the code memory space. In a 64-Kbyte device, for example, a post-increment read of address, FFFFh, will wrap the Table Pointer back to 000000h, rather than point to the unimplemented address, 010000h.

FIGURE 4-2: VERIFY CODE MEMORY FLOW



4.3 Verify Configuration Bits

A configuration address may be read and output on PGD via the 4-bit command, '1001'. Configuration data is read and written in a byte-wise fashion, so it is not necessary to merge two bytes into a word prior to a compare. The result may then be immediately compared to the appropriate configuration data in the programmer's memory for verification. Refer to **Section 4.1 "Read Code Memory, ID Locations and Configuration Bits"** for implementation details of reading configuration data.

4.4 Read Data EEPROM Memory

Data EEPROM is accessed, one byte at a time, via an Address Pointer (register pair: EEADRH:EEADR) and a data latch (EEDATA). Data EEPROM is read by loading EEADRH:EEADR with the desired memory location and initiating a memory read by appropriately configuring the EECON1 register. The data will be loaded into EEDATA, where it may be serially output on PGD via the 4-bit command, '0010' (Shift Out Data Holding register). A delay of P6 must be introduced after the falling edge of the 8th PGC of the operand to allow PGD to transition from an input to an output. During this time, PGC must be held low (see Figure 4-4).

The command sequence to read a single byte of data is shown in Table 4-2.

FIGURE 4-3: READ DATA EEPROM FLOW

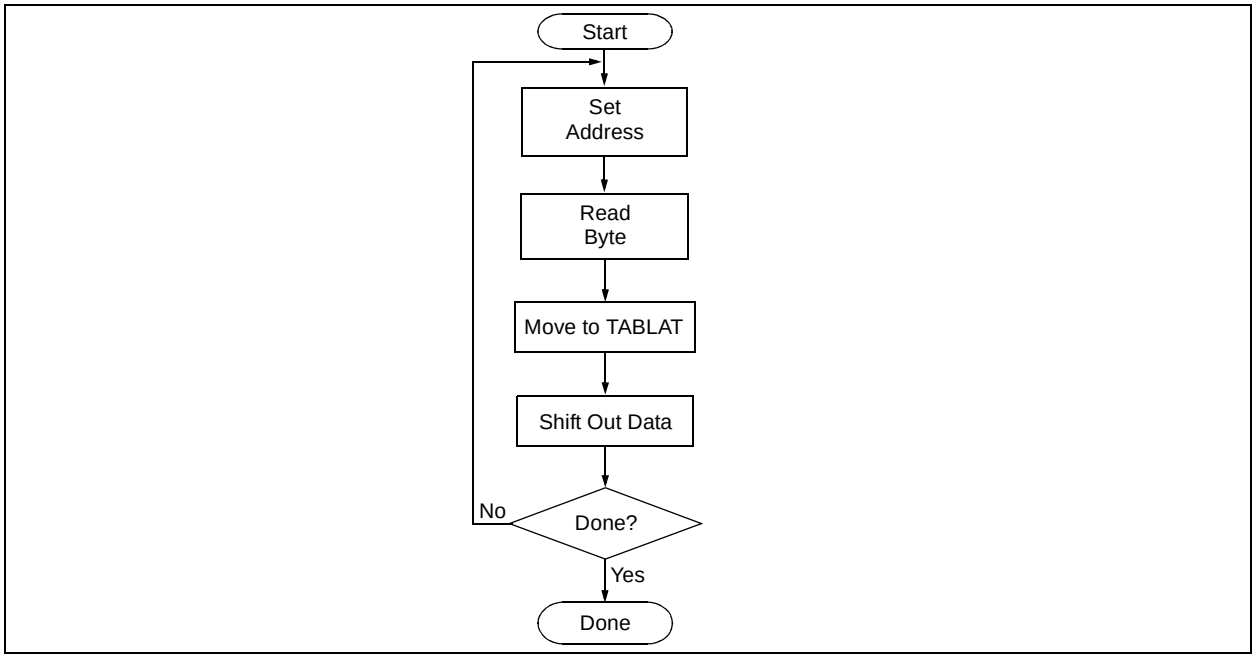


TABLE 4-2: READ DATA EEPROM MEMORY

4-Bit Command	Data Payload	Core Instruction
Step 1: Direct access to data EEPROM.		
0000 0000	9E A6 9C A6	BCF EECON1, EEPGD BCF EECON1, CFGS
Step 2: Set the data EEPROM Address Pointer.		
0000 0000 0000 0000	0E <Addr> 6E A9 OE <AddrH> 6E AA	MOVLW <Addr> MOVWF EEADR MOVLW <AddrH> MOVWF EEADRH
Step 3: Initiate a memory read.		
0000	80 A6	BSF EECON1, RD
Step 4: Load data into the Serial Data Holding register.		
0000 0000 0000 0010	50 A8 6E F5 00 00 <MSB><LSB>	MOVF EEDATA, W, 0 MOVWF TABLAT NOP Shift Out Data(1)

Note 1: The <LSB> is undefined. The <MSB> is the data.

TABLE 5-2: DEVICE ID VALUES

Device	Device ID Value	
	DEVID2	DEVID1
PIC18F2221	21h	011x xxxx
PIC18F2321	21h	001x xxxx
PIC18F2410	11h	011x xxxx
PIC18F2420	11h	010x xxxx(1)
PIC18F2423	11h	010x xxxx(2)
PIC18F2450	24h	001x xxxx
PIC18F2455	12h	011x xxxx
PIC18F2458	2Ah	011x xxxx
PIC18F2480	1Ah	111x xxxx
PIC18F2510	11h	001x xxxx
PIC18F2515	0Ch	111x xxxx
PIC18F2520	11h	000x xxxx(1)
PIC18F2523	11h	000x xxxx(2)
PIC18F2525	0Ch	110x xxxx
PIC18F2550	12h	010x xxxx
PIC18F2553	2Ah	010x xxxx
PIC18F2580	1Ah	110x xxxx
PIC18F2585	0Eh	111x xxxx
PIC18F2610	0Ch	101x xxxx
PIC18F2620	0Ch	100x xxxx
PIC18F2680	0Eh	110x xxxx
PIC18F2682	27h	000x xxxx
PIC18F2685	27h	001x xxxx
PIC18F4221	21h	010x xxxx
PIC18F4321	21h	000x xxxx
PIC18F4410	10h	111x xxxx
PIC18F4420	10h	110x xxxx(1)
PIC18F4423	10h	110x xxxx(2)
PIC18F4450	24h	000x xxxx
PIC18F4455	12h	001x xxxx
PIC18F4458	2Ah	001x xxxx
PIC18F4480	1Ah	101x xxxx
PIC18F4510	10h	101x xxxx
PIC18F4515	0Ch	011x xxxx
PIC18F4520	10h	100x xxxx(1)
PIC18F4523	10h	100x xxxx(2)
PIC18F4525	0Ch	010x xxxx
PIC18F4550	12h	000x xxxx
PIC18F4553	2Ah	000x xxxx
PIC18F4580	1Ah	100x xxxx

Legend: The ‘x’s in DEVID1 contain the device revision code.

Note 1: DEVID1 bit 4 is used to determine the device type (REV4 = 0).

2: DEVID1 bit 4 is used to determine the device type (REV4 = 1).

TABLE 5-2: DEVICE ID VALUES (CONTINUED)

Device	Device ID Value	
	DEVID2	DEVID1
PIC18F4585	0Eh	101x xxxx
PIC18F4610	0Ch	001x xxxx
PIC18F4620	0Ch	000x xxxx
PIC18F4680	0Eh	100x xxxx
PIC18F4682	27h	010x xxxx
PIC18F4685	27h	011x xxxx

Legend: The 'x's in DEVID1 contain the device revision code.
Note 1: DEVID1 bit 4 is used to determine the device type (REV4 = 0).
2: DEVID1 bit 4 is used to determine the device type (REV4 = 1).

TABLE 5-3: PIC18F2XXX/4XXX FAMILY BIT DESCRIPTIONS

Bit Name	Configuration Words	Description
IESO	CONFIG1H	Internal External Switchover bit 1 = Internal External Switchover mode is enabled 0 = Internal External Switchover mode is disabled
FCMEN	CONFIG1H	Fail-Safe Clock Monitor Enable bit 1 = Fail-Safe Clock Monitor is enabled 0 = Fail-Safe Clock Monitor is disabled
FOSC<3:0>	CONFIG1H	Oscillator Selection bits 11xx = External RC oscillator, CLKO function on RA6 101x = External RC oscillator, CLKO function on RA6 1001 = Internal RC oscillator, CLKO function on RA6, port function on RA7 1000 = Internal RC oscillator, port function on RA6, port function on RA7 0111 = External RC oscillator, port function on RA6 0110 = HS oscillator, PLL is enabled (Clock Frequency = 4 x FOSC1) 0101 = EC oscillator, port function on RA6 0100 = EC oscillator, CLKO function on RA6 0011 = External RC oscillator, CLKO function on RA6 0010 = HS oscillator 0001 = XT oscillator 0000 = LP oscillator
FOSC<3:0>	CONFIG1H	Oscillator Selection bits **(PIC18F2455/2550/4455/4550, PIC18F2458/2553/4458/4553 and PIC18F2450/4450 devices only)** 111x = HS oscillator, PLL is enabled, HS is used by USB 110x = HS oscillator, HS is used by USB 1011 = Internal oscillator, HS is used by USB 1010 = Internal oscillator, XT is used by USB 1001 = Internal oscillator, CLKO function on RA6, EC is used by USB 1000 = Internal oscillator, port function on RA6, EC is used by USB 0111 = EC oscillator, PLL is enabled, CLKO function on RA6, EC is used by USB 0110 = EC oscillator, PLL is enabled, port function on RA6, EC is used by USB 0101 = EC oscillator, CLKO function on RA6, EC is used by USB 0100 = EC oscillator, port function on RA6, EC is used by USB 001x = XT oscillator, PLL is enabled, XT is used by USB 000x = XT oscillator, XT is used by USB
USBDIV	CONFIG1L	USB Clock Selection bit **(PIC18F2455/2550/4455/4550, PIC18F2458/2553/4458/4553 and PIC18F2450/4450 devices only)** Selects the clock source for full-speed USB operation: 1 = USB clock source comes from the 96 MHz PLL divided by 2 0 = USB clock source comes directly from the OSC1/OSC2 oscillator block; no divide
CPUDIV<1:0>	CONFIG1L	CPU System Clock Selection bits **(PIC18F2455/2550/4455/4550, PIC18F2458/2553/4458/4553 and PIC18F2450/4450 devices only)** 11 = CPU system clock divided by 4 10 = CPU system clock divided by 3 01 = CPU system clock divided by 2 00 = No CPU system clock divide

Note 1: The BBSIZ bits, BBSIZ<1:0> and BBSIZ<2:1> bits, cannot be changed once any of the following code-protect bits are enabled: CPB or CP0, WRTB or WRT0, EBTRB or EBTR0.

2: Not available in PIC18FXX8X and PIC18F2450/4450 devices.

TABLE 5-3: PIC18F2XXX/4XXX FAMILY BIT DESCRIPTIONS (CONTINUED)

Bit Name	Configuration Words	Description
PLLDIV<2:0>	CONFIG1L	Oscillator Selection bits **(PIC18F2455/2550/4455/4550, PIC18F2458/2553/4458/4553 and PIC18F2450/4450 devices only)** Divider must be selected to provide a 4 MHz input into the 96 MHz PLL: 111 = Oscillator divided by 12 (48 MHz input) 110 = Oscillator divided by 10 (40 MHz input) 101 = Oscillator divided by 6 (24 MHz input) 100 = Oscillator divided by 5 (20 MHz input) 011 = Oscillator divided by 4 (16 MHz input) 010 = Oscillator divided by 3 (12 MHz input) 001 = Oscillator divided by 2 (8 MHz input) 000 = No divide – oscillator used directly (4 MHz input)
VREGEN	CONFIG2L	USB Voltage Regulator Enable bit **(PIC18F2455/2550/4455/4550, PIC18F2458/2553/4458/4553 and PIC18F2450/4450 devices only)** 1 = USB voltage regulator is enabled 0 = USB voltage regulator is disabled
BORV<1:0>	CONFIG2L	Brown-out Reset Voltage bits 11 = V_{BOR} is set to 2.0V 10 = V_{BOR} is set to 2.7V 01 = V_{BOR} is set to 4.2V 00 = V_{BOR} is set to 4.5V
BOREN<1:0>	CONFIG2L	Brown-out Reset Enable bits 11 = Brown-out Reset is enabled in hardware only (SBOREN is disabled) 10 = Brown-out Reset is enabled in hardware only and disabled in Sleep mode SBOREN is disabled) 01 = Brown-out Reset is enabled and controlled by software (SBOREN is enabled) 00 = Brown-out Reset is disabled in hardware and software
PWRTEN	CONFIG2L	Power-up Timer Enable bit 1 = PWRT is disabled 0 = PWRT is enabled
WDPS<3:0>	CONFIG2H	Watchdog Timer Postscaler Select bits 1111 = 1:32,768 1110 = 1:16,384 1101 = 1:8,192 1100 = 1:4,096 1011 = 1:2,048 1010 = 1:1,024 1001 = 1:512 1000 = 1:256 0111 = 1:128 0110 = 1:64 0101 = 1:32 0100 = 1:16 0011 = 1:8 0010 = 1:4 0001 = 1:2 0000 = 1:1

Note 1: The BBSIZ bits, BBSIZ<1:0> and BBSIZ<2:1> bits, cannot be changed once any of the following code-protect bits are enabled: CPB or CP0, WRTB or WRT0, EBTRB or EBTR0.

2: Not available in PIC18FXX8X and PIC18F2450/4450 devices.

5.6.3 ID LOCATIONS

Normally, the contents of these locations are defined by the user, but MPLAB® IDE provides the option of writing the device's unprotected 16-bit checksum in the 16 Most Significant bits of the ID locations (see MPLAB IDE Configure/ID Memory" menu). The lower 16 bits are not used and remain clear. This is the sum of all program memory contents and Configuration Words (appropriately masked) before any code protection is enabled.

If the user elects to define the contents of the ID locations, nothing about protected blocks can be known. If the user uses the preprotected checksum, provided by MPLAB IDE, an indirect characteristic of the programmed code is provided.

5.6.4 CODE PROTECTION

Blocks that are code-protected read back as all '0's and have no effect on checksum calculations. If any block is code-protected, then the contents of the ID locations are included in the checksum calculation.

All Configuration Words and the ID locations can always be read out normally, even when the device is fully code-protected. Checking the code protection settings in Configuration Words can direct which, if any, of the program memory blocks can be read, and if the ID locations should be used for checksum calculations.

TABLE 5-5: CONFIGURATION WORD MASKS FOR COMPUTING CHECKSUMS (CONTINUED)

Device	Configuration Word (CONFIGxx)													
	1L	1H	2L	2H	3L	3H	4L	4H	5L	5H	6L	6H	7L	7H
	Address (30000xh)													
	0h	1h	2h	3h	4h	5h	6h	7h	8h	9h	Ah	Bh	Ch	Dh
PIC18F4620	00	CF	1F	1F	00	87	C5	00	0F	C0	0F	E0	0F	40
PIC18F4680	00	CF	1F	1F	00	86	C5	00	0F	C0	0F	E0	0F	40
PIC18F4682	00	CF	1F	1F	00	86	C5	00	3F	C0	3F	E0	3F	40
PIC18F4685	00	CF	1F	1F	00	86	C5	00	3F	C0	3F	E0	3F	40

Legend: Shaded cells are unimplemented.

6.0 AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY TEST MODE (CONTINUED)

Standard Operating Conditions Operating Temperature: 25°C is recommended						
Param No.	**Sym**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
P11A	TDRWT	Data Write Polling Time	4	—	ms	
P12	THLD2	Input Data Hold Time from $\overline{\text{MCLR}}$/VPP/RE3 ↑	2	—	μs	
P13	TSET2	VDD ↑ Setup Time to $\overline{\text{MCLR}}$/VPP/RE3 ↑	100	—	ns	**(Note 2)**
P14	TVALID	Data Out Valid from PGC ↑	10	—	ns	
P15	TSET3	PGM ↑ Setup Time to $\overline{\text{MCLR}}$/VPP/RE3 ↑	2	—	μs	**(Note 2)**
P16	TDLY8	Delay Between Last PGC ↓ and $\overline{\text{MCLR}}$/VPP/RE3 ↓	0	—	s	
P17	THLD3	$\overline{\text{MCLR}}$/VPP/RE3 ↓ to VDD ↓	—	100	ns	
P18	THLD4	$\overline{\text{MCLR}}$/VPP/RE3 ↓ to PGM ↓	0	—	s	

Note 1: Do not allow excess time when transitioning $\overline{\text{MCLR}}$ between VIL and VIHH. This can cause spurious program executions to occur. The maximum transition time is:

1 TCY + TPWRT (if enabled) + 1024 TOSC (for LP, HS, HS/PLL and XT modes only) +
2 ms (for HS/PLL mode only) + 1.5 μs (for EC mode only)

where TCY is the instruction cycle time, TPWRT is the Power-up Timer period and TOSC is the oscillator period. For specific values, refer to the Electrical Characteristics section of the device data sheet for the particular device.

2: When ICPRT = 1, this specification also applies to ICVPP.

3: At 0°C-50°C.

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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